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R. Grader  
PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Shinji Isokawa      Examiner: Wai Sing Louie  
Serial No.: 09/731,889      Group Art Unit: 2814  
Confirmation No.: 1026      Docket No.: 362-51  
Filed: December 7, 2000      Dated: May 3, 2002  
For: CHIP-TYPE SEMICONDUCTOR  
LIGHT-EMITTING DEVICE

Commissioner for Patents  
Washington, DC 20231

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D.C. 20231  
On May 3, 2002*

*Signature: *

REPLY TO NON-FINAL OFFICE ACTION

Sir:

In response to the non-final Office Action mailed February 7, 2002, a reply to which is due May 7, 2002, please amend the above-identified application as follows:

IN THE SPECIFICATION:

At page 4, replace the paragraph beginning at line 18 with the following:

*31*  
Furthermore, a translucent-synthetic-resin mold 24 is formed on the upper surface of the substrate 12. The mold encapsulates the protrusion 14b, protrusion 16b, pad 16c, LED chip 20 and metal wire 22.

IN THE CLAIMS:

Please amend Claims 1 and 2 by rewriting the same as follows:

*Yee  
B1  
B2*

1. (Amended) A chip-type semiconductor light-emitting device, comprising:  
a pair of electrodes, at least one of said pair of electrodes including an inner portion and an outer portion;

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